

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6431707

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
STEFAN HECKELMANN	11/18/2020
ANDREAS RUDOLPH	12/03/2020
ALEXANDER TONKIKH	11/22/2020
RECEIVING PARTY DATA	
Name:	OSRAM OLED GMBH
Street Address:	LEIBNIZSTR. 4
City:	REGENSBURG
State/Country:	GERMANY
Postal Code:	93055
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17054488
CORRESPONDENCE DATA	
Fax Number:	(703)997-4905
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	MH2 TECHNOLOGY LAW GROUP, LLP
Address Line 1:	1951 KIDWELL DRIVE
Address Line 2:	SUITE 310
Address Line 4:	TYSONS CORNER, VIRGINIA 22182
ATTORNEY DOCKET NUMBER:	0357.0033-US
NAME OF SUBMITTER:	KAILEY A. MCNEILL
SIGNATURE:	/kailey a mcneill/
DATE SIGNED:	12/04/2020
Total Attachments: 6	
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ASSIGNMENT AND DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS I/We, the below named inventor(s), (hereinafter referred to as Assignor(s)), have made an invention claimed and/or described in an application for United States Letters Patent entitled:

OPTOELECTRONIC SEMICONDUCTOR CHIP

filed herewith, as United States Application No. 17/054,488, filed on November 10, 2020

WHEREAS, OSRAM OLED GMBH
a corporation of Regensburg, DE

whose post office address is Leibnizstr. 4 Regensburg, DE 93055

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions and continuations thereof, and any provisional application whose benefit is claimed therefrom, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, as well as all rights to claim priority on the basis of this application in any foreign country, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof, and I/We hereby authorize and request the Director of the United States Patent and Trademark Office and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

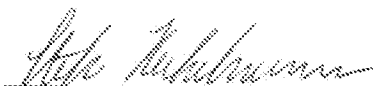
AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the Assignee's agents, MH2 Technology Law Group LLP, whose address is 1951 Kidwell Drive, Suite 310, Tysons Corner, VA 22182, to insert hereon any identification necessary or desirable for recordation of this document, including the filing date and application number of said application when known.

As a named inventor below, I hereby declare that: (1) this declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my residence and mailing address are as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.



Stefan Heckelmann

18. November 2020

DATE

Andreas Rudolph

DATE

Alexander Tonkikh

DATE

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AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

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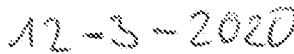
IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Stefan Heckelmann

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Andreas Rudolph



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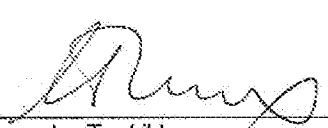
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Stefan Heckelmann

DATE

Andreas Rudolph

DATE



Alexander Tonkikh

22.11.2020
DATE